

*CLAIM AMENDMENTS*

1. (Currently Amended) A system for polishing one or more layers of a multi-layer substrate that includes a first metal layer and a second layer comprising (i) a liquid carrier, (ii) at least one oxidizing agent, (iii) at least one polishing additive that increases the rate at which the system polishes at least one layer of the substrate, wherein the polishing additive is selected from the group consisting of pyrophosphates, condensed phosphates, diphosphonic acids, tri-phosphonic acids, poly-phosphonic acids, phosphonoacetic acids, and salts thereof, aminoethylethanolamine, polyethyleneimine, ~~amino alcohols, amides,~~ imines, imino acids, nitriles, nitros, thioesters, thioethers, carbothiolic acids, carbothionic acids, thiocarboxylic acids, thiosalicylic acids, and mixtures thereof, (iv) at least one passivation film forming agent, and (v) a polishing pad and/or an abrasive.
2. (Original) The system of claim 1, wherein the liquid carrier is a nonaqueous solvent.
3. (Original) The system of claim 1, wherein the liquid carrier is water.
4. (Original) The system of claim 3, wherein the system comprises an abrasive suspended in the liquid carrier.
5. (Original) The system of claim 3, wherein the abrasive is fixed on the polishing pad.
6. (Original) The system of claim 3, wherein no abrasive is present in the system, and the polishing pad is a non-abrasive pad.
7. (Canceled)
8. (Previously Presented) The system of claim 3, wherein at least one oxidizing agent is a peroxide, and at least one passivation film forming agent comprises one or more 5-6 member heterocyclic nitrogen-containing rings.
9. (Previously Presented) The system of claim 3, wherein at least one polishing additive is selected from the group consisting of ethylene di-phosphonic acid, 1-hydroxyethylidene-1,1-di-phosphonic acid, and a mixture thereof.

10-15. (Canceled)

16. (Previously Presented) The system of claim 9, wherein at least one oxidizing agent is a peroxide, and at least one passivation film forming agent comprises one or more 5-6 member heterocyclic nitrogen-containing rings.

17. (Original) The system of claim 3, wherein at least one polishing additive is both (a) a compound selected from the group consisting of pyrophosphates, condensed phosphates, phosphonic acids and salts thereof, and (b) a compound selected from the group consisting of amines, amino alcohols, amides, imines, imino acids, nitriles, and nitros.

18. (Currently Amended) The system of claim 3, wherein at least one polishing additive is both (a) a compound selected from the group consisting of amines, amino alcohols, amides, imines, imino acids, nitriles, and nitros, and (b) a compound selected from the group consisting of thiols, thioesters, ~~and~~ thioethers, carbothiolic acids, carbothionic acids, thiocarboxylic acids, and thiosalicylic acids.

19. (Original) The system of claim 17, wherein at least one polishing additive is selected from the group consisting of 2-aminoethyl phosphonic acid, amino(trimethylenephosphonic acid), diethylenetriaminepenta(methylenephosphonic acid), hexamethylenediaminetetra(methylene phosphonic acid), and mixtures thereof.

20. (Original) The system of claim 3, wherein the system further comprises a source of ammonia.

21. (Original) The system of claim 20, wherein the system comprises (i) aminotri-(methylenephosphonic acid) and (ii) ammonia or an ammonium salt.

22. (Original) The system of claim 3, wherein the system further comprises at least one stopping compound.

23. (Original) The system of claim 3, wherein the system further comprises at least one polymeric compound that reduces the polishing rate of at least one layer associated with the substrate.

24. (Previously Presented) The system of claim 3, wherein at least one passivation film-forming agent is selected from the group consisting of 1,2,3-triazole, 1,2,4-triazole, benzotriazole, benzimidazole, benzothiazole, and hydroxy-, amino-, imino-, carboxy-, mercapto-, nitro-, urea-, thiourea-, or alkyl-substituted derivatives thereof.

25. (Original) The system of claim 3, wherein the abrasive is a metal oxide abrasive.

26. (Original) The system of claim 25, wherein the abrasive is selected from the group consisting of alumina, ceria, germania, silica, titania, zirconia, and coformed products thereof, and mixtures thereof.

27. (Original) The system of claim 26, wherein the abrasive is alumina.

28-31. (Canceled)

32. (Original) The system of claim 1, wherein at least one polishing additive is iminodiacetic acid.

33. (Original) The system of claim 32, wherein the system further comprises at least one stopping compound.

34. (Original) The system of claim 32, wherein the system further comprises at least one polymeric compound that reduces the polishing rate of at least one layer associated with the substrate.

35. (Original) The system of claim 22, wherein the system further comprises ammonia or an ammonium salt.

36-39. (Canceled)